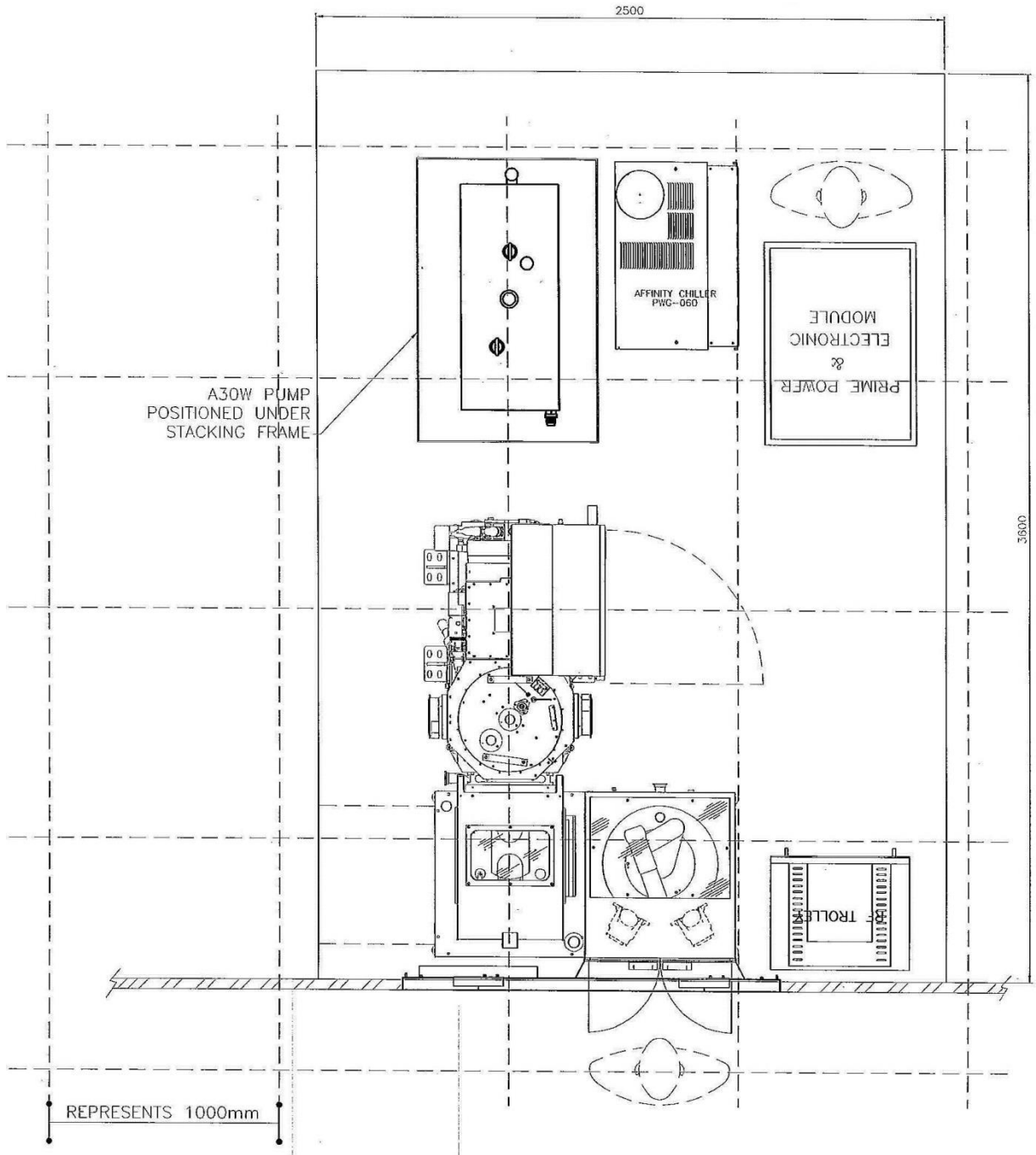


STS MACS ICP^{HR} Etch System

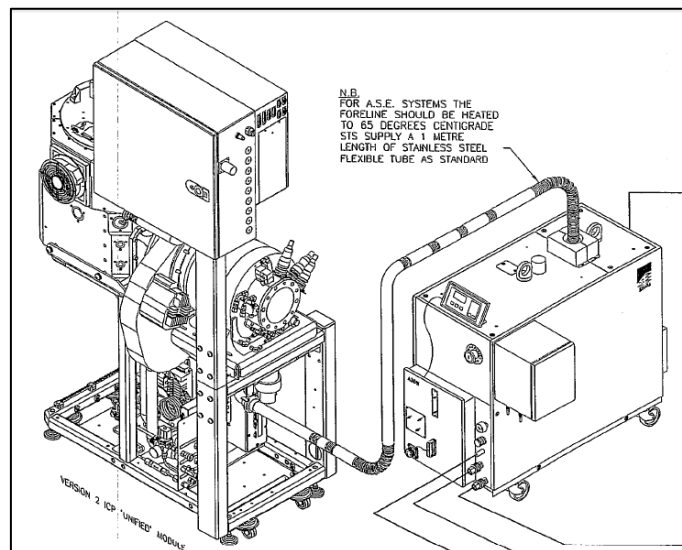
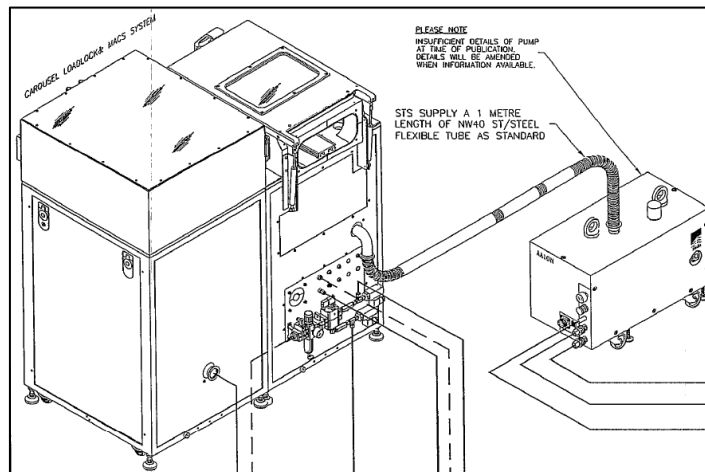


FOOTPRINT LAYOUT OF MACS ICP (HR)

EQUIPMENT DATASHEET

Item List	Description
Manufacturer:	STS
Model:	MACS ICP ^{HR}
Wafer Size:	150/200mm. The current status is mainly 200mm.
Tool Condition:	Used
Chamber Quantity:	1 Chamber
Volts / Hz/Ph:	380 Volts / 60 Hz ,40 Amps/phase
Vintage:	2003

➤ System General View :



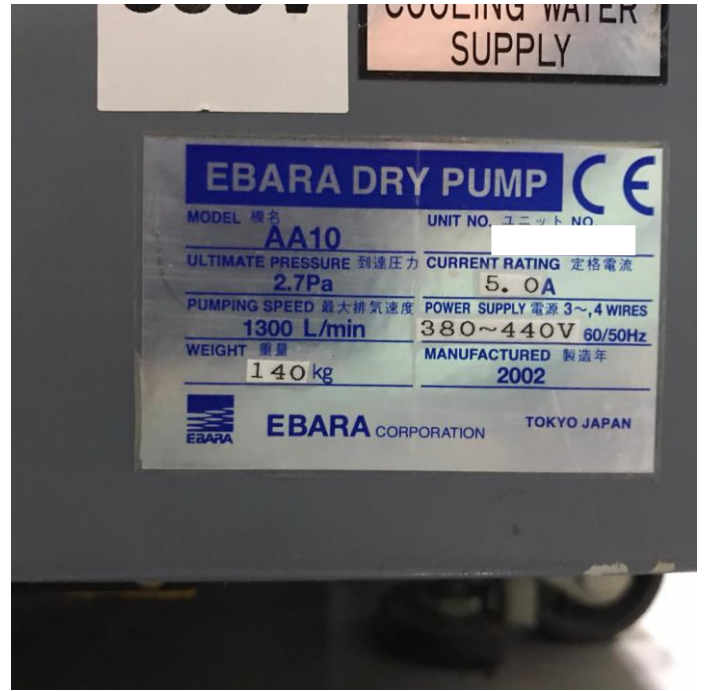
EQUIPMENT DATASHEET

- System Components and Configuration
- Advanced Silicon Etch (ASE) with Bosch process
- HR Chamber for High Rate Etch
- Set up for 200mm wafer (150mm-200mm capable)
- MACs Loader for Cassette to Cassette operation (2 load stations)
- Carousel vacuum load lock
- Helium Backside Cooling (HBC)
- HBC Assy: ICP V2
- Clamp Type: Standard WTC
- Lower Electrode: ICP WTC Tripod Lift
- Chamber Insulation Jackets: None
- **RF Generators:**
 1. Coil RF Power : ENI GHW-50Z 5kw
 2. Platen RF Power : ENI ACG-3B 13.56MHZ, 300W
- Gases: C_4F_8 (200 sccm) 、 SF_6 (1000 sccm) 、 O_2 (2000 sccm) 、 N_2 (500 sccm)
- **Vacuum System**
 1. Turbo Pump: LEYBOLD MAG 2000
 2. Load Lock Pump: EBARA AA10
 3. Chamber Pump: EBARA A30W
- **Chiller: Affinity PWG-060L-BE27CBD2**

Photos:



EQUIPMENT DATASHEET



EQUIPMENT DATASHEET

